

ABSTRACT OF THE DISCLOSURE

A semiconductor packaging structure. The structure comprises a chip, a lead frame, and a plurality of wires. The chip comprises an active surface and an opposing non-active surface, the active surface comprising a central area and a peripheral area having a plurality of bonding pads. The lead frame comprises a plurality of the leads, a plurality of tie bars, and a chip paddle. The tie bars is connected with the chip paddle and attached to the active surface of the chip in such a way as to avoid contact with the bonding pads. As well, the wires electrically connect with the bonding pad and the leads.